



DXT2222A

40V NPN SURFACE MOUNT TRANSISTOR IN SOT89

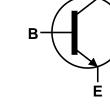
Features

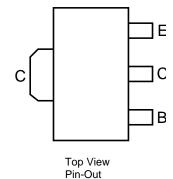
- BV_{CEO} > 40V
- I_C = 600mA High Collector Current
- Complementary PNP Type: DXT2907A
- Ideal for Medium Power Switching or Amplification Applications
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SOT89
- Case Material: Molded Plastic, "Green" Molding Compound;
 UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 (§3)
- Weight: 0.072 grams (Approximate)







Top View

Device Symbol

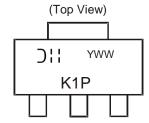
Ordering Information (Note 4)

Product	Compliance	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DXT2222A-13	AEC-Q101	K1P	13	12	2,500

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen and Antimony free, "Green" and Lead-Free.
- 3. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



OH = Manufacturer's Code Marking
K1P = Product Type Marking Code:
YWW = Date Code Marking
Y = Last Digit of Year ex: 1 = 2011
WW = Week Code 01 - 52



Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	75	V
Collector-Emitter Voltage	V _{CEO}	40	V
Emitter-Base Voltage	V_{EBO}	6	V
Peak Pulse Current	I _{CM}	800	mA
Continuous Collector Current	Ic	600	mA

Thermal Characteristics

Characteristic	Symbol	Value	Unit		
Power Dissipation	(Note 5)	В	0.75	- W	
Power Dissipation	(Note 6)	P _D	1.2		
Thermal Resistance, Junction to Ambient Air	(Note 5)	Б	166	°C/W	
Thermal Resistance, Junction to Ambient Air	(Note 6)	$R_{ hetaJA}$	104	C/VV	
Operating and Storage Temperature Range	T _j , T _{STG}	-55 to +150	°C		

ESD Ratings (Note 7)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	С

Notes:

- 5. For a device mounted with the exposed collector pad on minimum recommended pad layout 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.

 6. Same as Note 5, except the device is mounted with the exposed collector pad on 25mm x 25mm 1oz copper.
- 7. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

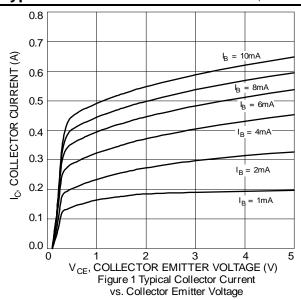


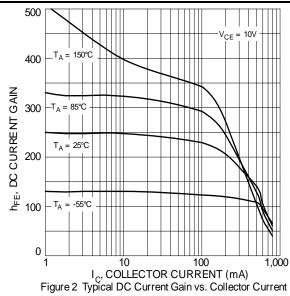
Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Conditions
OFF CHARACTERISTICS (Note 8)					
Collector-Base Breakdown Voltage	BV _{CBO}	75	_	V	$I_C = 10\mu A$
Collector-Emitter Breakdown Voltage	BV _{CEO}	40	_	V	I _C = 10mA
Emitter-Base Breakdown Voltage	BV _{EBO}	6.0	_	V	$I_E = 10\mu A$
Collector Cutoff Current	I _{CBO}		10	nA μA	$V_{CB} = 60V$ $V_{CB} = 60V$, $T_A = +150$ °C
Collector Cutoff Current	I _{CEX}		10	nA	$V_{CE} = 60V, V_{EB(OFF)} = 3.0V$
Emitter Cutoff Current	I _{EBO}		10	nA	V _{EB} = 3.0V
Base Cutoff Current	I _{BL}	_	20	nA	$V_{CE} = 60V, V_{EB(OFF)} = 3.0V$
ON CHARACTERISTICS (Note 8)				•	\.
DC Current Gain	h _{FE}	35 50 75 100 40 35 50	300 — —	_	$\begin{split} I_C &= 100 \mu A, \ V_{CE} = 10 V \\ I_C &= 1.0 mA, \ V_{CE} = 10 V \\ I_C &= 10 mA, \ V_{CE} = 10 V \\ I_C &= 150 mA, \ V_{CE} = 10 V \\ I_C &= 500 mA, \ V_{CE} = 10 V \\ I_C &= 10 mA, \ V_{CE} = 10 V, \ T_A = -55 ^{\circ} C \\ I_C &= 150 mA, \ V_{CE} = 1.0 V \end{split}$
Collector-Emitter Saturation Voltage	V _{CE(SAT)}		0.3 1.0	V	$I_C = 150$ mA, $I_B = 15$ mA $I_C = 500$ mA, $I_B = 50$ mA
Base-Emitter Saturation Voltage	V _{BE(SAT)}	0.6	1.2 2.0	V	$I_C = 150$ mA, $I_B = 15$ mA $I_C = 500$ mA, $I_B = 50$ mA
SMALL SIGNAL CHARACTERISTICS					
Output Capacitance	C _{obo}		8	pF	$V_{CB} = 10V, f = 1.0MHz$
Input Capacitance	C _{ibo}		25	pF	$V_{EB} = 0.5V, f = 1.0MHz$
Current Gain-Bandwidth Product	f⊤	300	_	MHz	V _{CE} = 20V, I _C = 20mA, f = 100MHz
Noise Figure	NF		4.0	dB	$V_{CE} = 10V, I_{C} = 150\mu A,$ $R_{S} = 1.0k\Omega, f = 1.0kHz$
SWITCHING CHARACTERISTICS					
Delay Time	t _d	_	10	ns	$V_{CC} = 30V, I_C = 150mA,$
Rise Time	t _r	_	25	ns	$V_{EB(off)} = 0.5V, I_{B1} = 15mA$
Storage Time	ts	_	225	ns	$V_{CC} = 30V, I_C = 150mA,$
Fall Time	t _f	_	60	ns	$I_{B1} = I_{B2} = 15\text{mA}$

8. Measured under pulsed conditions. Pulse width = 300µs. Duty cycle ≤2%. Note:

Typical Electrical Characteristics (@TA = +25°C unless otherwise specified.)







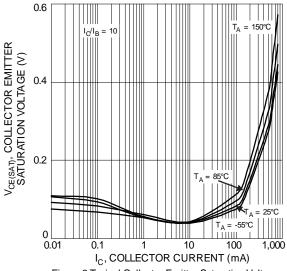


Figure 3 Typical Collector Emitter Saturation Voltage vs. Collector Current

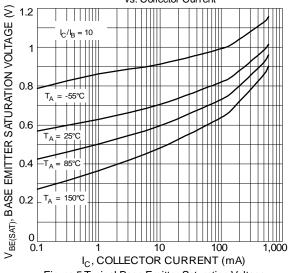
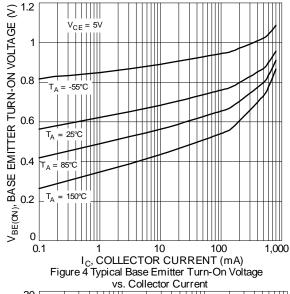


Figure 5 Typical Base Emitter Saturation Voltage vs. Collector Current 500 450 GAIN-BANDWIDTH PRODUCT (MHz) 400 350 300 250 200 150 100 V_{CE} = 20V f = 100MHz Ţ 50 0 0 100 Figure 7 Typical Gain-Bandwidth Product

vs. Collector Current



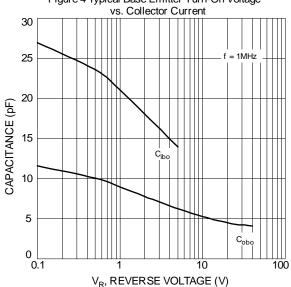
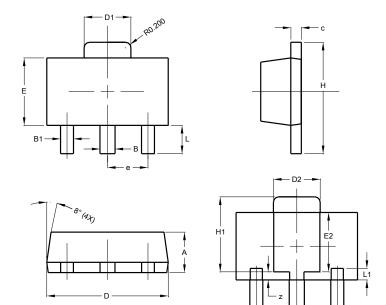


Figure 6 Typical Capacitance Characteristics



Package Outline Dimensions

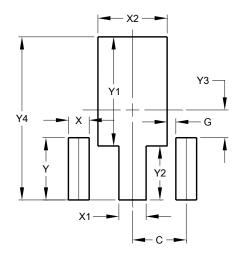
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



SOT89						
Dim	Min Max		Тур			
Α	1.40	1.60	1.50			
В	0.50	0.62	0.56			
B1	0.42	0.54	0.48			
С	0.35	0.43	0.38			
D	4.40	4.60	4.50			
D1	1.62	1.83	1.733			
D2	1.61	1.81	1.71			
Е	2.40	2.60	2.50			
E2	2.05	2.35	2.20			
е	1	1.50				
Н	3.95	4.25	4.10			
H1	2.63	2.93	2.78			
L	0.90	1.20	1.05			
L1	0.427 REF					
Z	0.30 REF					
All Dimensions in mm						

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)		
С	1.500		
G	0.244		
Х	0.580		
X1	0.760		
X2	1.933		
Υ	1.730		
Y1	3.030		
Y2	1.500		
Y3	0.770		
Y4	4.530		



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